# PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

## **CONVEYING PARTY DATA**

Name	Execution Date
Woon-Seong KWON	11/19/2007
Yong-Hwan KWON	11/19/2007
Un-Byoung KANG	11/19/2007
Chung-Sun LEE	11/19/2007
Hyung-Sun JANG	11/19/2007

#### **RECEIVING PARTY DATA**

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City:	Gyeonggi-do	
State/Country:	KOREA, DEMOCRATIC PEOPLE'S REPUBLIC OF	

## PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11952426

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NAME OF SUBMITTER:	Hosoon Lee

Total Attachments: 2

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PATENT APPLICATION Docket No.: 9898-610 Client Ref. No.: SS-29965-US

#### ASSIGNMENT

U.S.A. Patent Application
Sole or Joint
For Inventions Made Outside U.S.A.
Executed With Application

In consideration of the sum of Ten Dollars (10.00) and other good and valuable considerations paid to each of the undersigned, to wit:

- (1) Woon-Seong KWON
- (2) Yong-Hwan KWON
- (3) Un-Byoung KANG
- (4) Chung-Sun LEE
- (5) Hyung-Sun JANG

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the receipt and sufficiency of which are hereby acknowledged by the undersigned who hereby sell(s), assign(s) and transfer(s) unto:

SAMSUNG ELECTRONICS CO., LTD. 416 MAETAN-DONG, YEONGTONG-GU SUWON-SI, GYEONGGI-DO REPUBLIC OF KOREA

(hereinafter designated "ASSIGNEE") the entire right, title and interest in and to the invention as defined in 35 USC §100, for the United States of America, the invention entitled:

# STACK TYPE SEMICONDUCTOR CHIP PACKAGE HAVING DIFFERENT TYPE OF CHIPS AND FABRICATION METHOD THEREOF

for which an application for Letters Patent of the United States of America has been executed even date herewith by the undersigned, and in and to any and all divisionals, continuations, substitutes, and reissues thereof; and all resulting patents and the undersigned hereby authorizes and requests the United States Assistant Commissioner of Patents to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

And the undersigned hereby agrees to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE'S full protection and title in and to the invention hereby transferred.

I

REEL: 020213 FRAME: 0037

Please sign
concurrently
with Oath or Declaration
and Power of Attorney

#### SIGNED ON THE DATES INDICATED BESIDE OUR SIGNATURES:

INVENTOR(S)	<u>DATE SIGNED</u>	WITNESSED
(1) Woon-Seong KWON	11/19/2007	
(2) Yong-Hwan KWON	11/19/2007	
(3) LM Cery Un-Byoung KANG	01/19/2000	
(4) Chung-Sun LEE	11/19/2007	P-WATER BALL ALL A
(5) Hyung-Sun JANG	11/19/201)	

PLEASE RETURN RECORDED ASSIGNMENT TO:

Alan T. McCollom Marger Johnson & McCollom 210 S.W. Morrison Street, Suite 400 Portland, OR 97204

**RECORDED: 12/07/2007**